

#### **Application Information**

**Application number::** 10/123,751

Filing Date:: 04/16/2002

Application Type:: Regular

Subject Matter:: Utility

Suggested classification::

**Suggested Group Art Unit::** 

CD-ROM or CD-R?:: None

Computer Readable Form (CRF)?:: No

Title:: METHOD OF ULTRA-LOW ENERGY ION

IMPLANTATION TO FORM ALLOY LAYERS

IN COPPER

**Attorney Docket Number::** 039153-0529 (G1234)

Request for Early Publication?:: No

Request for Non-Publication?:: No

**Suggested Drawing Figure::** 

**Total Drawing Sheets::** 3

Small Entity?:: No

Petition included?:: No

Secrecy Order in Parent Appl.?:: No

## Applicant Information

**Applicant Authority Type::** Inventor

Primary Citizenship Country:: United Kingdom

Status:: Full Capacity

Given Name::	Ercan			
Family Name::	Adem			
City of Residence::	Sunnyvale			
State or Province of	CA			
Residence::				
Country of Residence::	US			
Street of mailing address::	729 Liverpool Way			
City of mailing address::	Sunnyvale			
State or Province of mailing	CA			
address::				
Postal or Zip Code of mailing	94087			
address::				
Correspondence Information				
Correspondence Customer Nu	mber::	26371		
E-Mail address::		PTOMailMadison@fo	oley.com	
Representative Information				
Representative Customer				
Number::				

# **Domestic Priority Information**

Application::	Continuity Type::	Parent	Parent Filing
		Application::	Date::
This Application	Continuation of	10/123,751	04/16/2002

## Foreign Priority Information

Country::	Application	Filing Date::	Priority Claimed::
	number::		

### **Assignee Information**

Assignee Name::

Advanced Micro Devices, Inc.